# PME271Y, Metallized Impregnated Paper, Class Y2, 250 VAC



**Overview** Applications

Multilayer, metallized paper, encapsulated and impregnated in self-extinguishing material that meets the requirements of UL 94 V=0.

For worldwide use as an electromagnetic interference suppressor in all Y2 applications, line-to-earth.

#### **Benefits**

Approvals: ENEC, UL, cUL, CQC
 Rated voltage: 250 VAC 50/60 Hz
 Capacitance range: 0.001 – 0.1 μF
 Lead spacing: 10.2 – 25.4 mm

Lead spacing: 10.2 – 25.4 mn
 Capacitance tolerance: ±20%

Climatic category: 40/100/56/B, IEC 60068-1

Tape & Reel packaging in accordance with IEC 60286-2

· RoHS compliance and lead-free terminations

Operating temperature range of -40°C to +100°C

• 100% screening factory test at 3,000 VDC

Highest possible safety regarding active and passive flammability



# **Customer Part Number System**

PME271	Υ	410	M	R30
Series	Rated Voltage (VAC)	Capacitance Code (pF)	Capacitance Tolerance	Packaging
Y2, Metallized Paper	Y = 250	The last two digits represent significant figures. The first digit specifies the total number of digits.	M = ±20%	See Ordering Options Table

# **KEMET Internal Part Number System**

Р	271	Н	E	102	M	250	Α
Capacitor Class	Series	Lead Spacing (mm)	Size Code	Capacitance Code (pF)	Capacitance Tolerance	Rated Voltage (VAC)	Lead and Packaging Code
P = Paper	Y2, Metallized Paper	H = 10.2 Q = 15.2 C = 20.3 E = 25.4	See Dimension Table	First two digits represent significant figures. Third digit specifies number of zeros.	M = ±20%	250 = 250	See Ordering Options Table

One world. One KEMET



#### **Benefits cont.**

- Excellent self-healing properties ensure long life, even when subjected to frequent overvoltages
- · Good resistance to ionization due to impregnated dielectric
- · High dv/dt capability

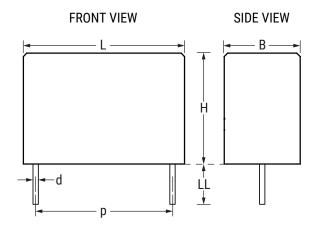
 Impregnated paper that ensures excellent stability and reliability, particularly in applications with continuous operation

# **Ordering Options Table**

Lead Spacing Nominal (mm)	Type of Leads and Packaging	Lead Length (mm)	KEMET Lead and Packaging Code	Legacy Lead and Packaging Code
	Standard Lead and Packaging Options			
	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
10.2	Bulk (Bag) – Maximum Length Leads	30 +5/-0	Α	R30
10.2	Tape & Reel (Standard Reel)	$H_0 = 18.5 \pm 0.5$	L	R19T0
	Other Lead and Packaging Options			
	Tape & Reel (Large Reel)	$H_0 = 18.5 \pm 0.5$	Р	R19T1
Native 10.2 formed to 7.5	Ammo Pack	$H_0 = 18.5 \pm 0.5$	LAF3	R30XA
	Standard Lead and Packaging Options			
	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
45.0	Bulk (Bag) – Maximum Length Leads	30 +5/-0	Α	R30
15.2	Tape & Reel (Standard Reel)	$H_0 = 18.5 \pm 0.5$	L	R19T0
	Other Lead and Packaging Options			
	Tape & Reel (Large Reel)	H <sub>0</sub> = 18.5 ±0.5	Р	R19T1
	Ohandard and Barbarian Ontions			
	Standard Lead and Packaging Options	6 : 0 / 1	0	DOC
	Bulk (Bag) - Short Leads	6 +0/-1	C	R06 R30
20.3	Bulk (Bag) – Maximum Length Leads	30 +5/-0	A	
	Tape & Reel (Standard Reel)	H <sub>0</sub> = 18.5 ±0.5	L	R19T0
	Other Lead and Packaging Options	U = 10 E ±0 E	P	R19T1
	Tape & Reel (Large Reel)	$H_0 = 18.5 \pm 0.5$	Γ	KIYII
	Standard Lead and Packaging Options			
25.4	Bulk (Bag) – Short Leads	6 +0/-1	С	R06
	Bulk (Bag) – Maximum Length Leads	30 +5/-0	А	R30



# **Dimensions - Millimeters**



	p	I	В	I	Н	L		d	
Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance	Nominal	Tolerance
10.2	±0.4	3.9	Maximum	7.5	Maximum	13.5	Maximum	0.6	±0.05
10.2	±0.4	4.1	Maximum	8.2	Maximum	13.5	Maximum	0.6	±0.05
10.2	±0.4	5.1	Maximum	10.5	Maximum	13.5	Maximum	0.6	±0.05
15.2	±0.4	5.2	Maximum	10.5	Maximum	18.5	Maximum	0.8	±0.05
15.2	±0.4	5.5	Maximum	11.0	Maximum	18.5	Maximum	0.8	±0.05
15.2	±0.4	7.3	Maximum	13.0	Maximum	18.5	Maximum	0.8	±0.05
20.3	±0.4	7.6	Maximum	14.0	Maximum	24.0	Maximum	0.8	±0.05
20.3	±0.4	9.0	Maximum	15.0	Maximum	24.0	Maximum	0.8	±0.05
20.3	±0.4	11.3	Maximum	16.5	Maximum	24.0	Maximum	0.8	±0.05
25.4	±0.4	12.1	Maximum	19.0	Maximum	30.5	Maximum	1.0	±0.05
			Note: See the Or	doring Ontions	Table for lead lan	ath (II) antions			*

Note: See the Ordering Options Table for lead length (LL) options.



# **Performance Characteristics**

Rated Voltage	250 VAC 50/60 Hz				
Capacitance Range	0.001 – 0.1 μF				
Capacitance Tolerance	±20%				
Temperature Range	-40°C to +100°C				
Climatic Category	40/100/56/B				
Approvals	ENEC, UL, CSA, CQC				
Discinction Factor	Maximum Values at +23°C				
Dissipation Factor	1 kHz	1.3%			
Test Voltage Between Terminals	The 100% screening factory test is carried out at 3,000 VDC. The voltage level is selected to meet the requirements in applicable equipment standards. All electrical characteristics are checked after the test. This test may not be repeated due to potential capacitor damage. KEMET is not liable for any failures that result from repeating the test.				
Insulation Resistance	Minimum Value Between Terminals				
ilisulation resistance	12,000 ΜΩ				
In DC Applications	Recommended voltage ≤ 1,000 V	DC			

# **Environmental Test Data**

Test	IEC Publication	Procedure
Vibration	IEC 60068-2-6 Test Fc	3 directions at 2 hours each 10 - 500 Hz at 0.75 mm or 98 m/s <sup>2</sup>
Bump	IEC 60068-2-29 Test Eb	4,000 bumps at 390 m/s <sup>2</sup>
Solderability	IEC 60068-2-20 Test Ta	Solder globule method
Active flammability	IEC 60384-14	
Passive flammability	IEC 60384-14	Needle-flame test
Humidity	IEC 60068-2-3 Test Ca	+40°C and 90 – 95% R.H.



# **Approvals**

Mark	Specification	File Number		
	EN/IEC 60384-14	SE/0140-27D		
c <b>FL</b> us	UL 60384-14 CAN/CSA-E60384-14-09	E73869		
COC	CQC	14001107140		

# **Environmental Compliance**

All KEMET EMI capacitors are RoHS compliant.



# **Table 1 – Ratings & Part Number Reference**

Capacitance Value (µF)	Maximum Dimensions in mm			Lead Spacing (p)	f <sub>o</sub> (MHz)	dV/dt (V/μs)	KEMET Internal Part Number	Customer Part Number
value (µr)	В	Н	L	Spacing (p)	(IVITIZ)	( v/µs)	Part Number	Part Number
0.0010	3.9	7.5	13.5	10.2	53	2,000	P271HE102M250(1)	PME271Y410M(1)
0.0015	3.9	7.5	13.5	10.2	44	2,000	P271HE152M250(1)	PME271Y415M(1)
0.0022	3.9	7.5	13.5	10.2	37	2,000	P271HE222M250(1)	PME271Y422M(1)
0.0033	4.1	8.2	13.5	10.2	30	2,000	P271HH332M250(1)	PME271Y433M(1)
0.0047	5.1	10.5	13.5	10.2	24	2,000	P271HL472M250(1)	PME271Y447M(1)
0.0068	5.2	10.5	18.5	15.2	19	1,400	P271QE682M250(1)	PME271Y468M(1)
0.0100	5.2	10.5	18.5	15.2	16	1,400	P271QE103M250(1)	PME271Y510M(1)
0.0150	5.5	11.0	18.5	15.2	13	1,400	P271QH153M250(1)	PME271Y515M(1)
0.0220	7.3	13.0	18.5	15.2	9.8	1,400	P271QM223M250(1)	PME271Y522M(1)
0.0330	7.6	14.0	24.0	20.3	7.0	1,000	P271CE333M250(1)	PME271Y533M(1)
0.0470	9.0	15.0	24.0	20.3	6.0	1,000	P271CJ473M250(1)	PME271Y547M(1)
0.0680	11.3	16.5	24.0	20.3	4.6	600	P271CP683M250(1)	PME271Y568M(1)
0.1000	12.1	19.0	30.5	25.4	3.9	400	P271EJ104M250(1)	PME271Y610M(1)
Capacitance Value (µF)	B (mm)	H (mm)	L (mm)	Lead Spacing (p)	f <sub>o</sub> (MHz)	dV/dt (V/µs)	KEMET Internal Part Number	Customer Part Number

<sup>(1)</sup> Insert ordering code for lead type and packaging. See Ordering Options Table for available options.



# **Soldering Process**

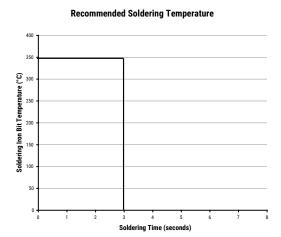
The implementation of the RoHS directive has resulted in the selection of SnAuCu (SAC) alloys or SnCu alloys as a primary solder. This has increased the liquidus temperature from  $183^{\circ}$ C for SnPb eutectic alloy to  $217 - 221^{\circ}$ C for the new alloys. As a result, the heat stress to the components, even in wave soldering, has increased considerably due to higher pre-heat and wave temperatures. Polypropylene capacitors are especially sensitive to heat (the melting point of polypropylene is  $160 - 170^{\circ}$ C). Wave soldering can be destructive, especially for mechanically small polypropylene capacitors (with lead spacing of 5 - 15 mm). Great care must be taken during soldering. The recommended solder profiles from KEMET should be used. Consult KEMET with any questions. In general, the wave soldering curve from IEC Publication 61760-1 Edition 2 serves as a solid guideline for successful soldering. See Figure 1.

Reflow soldering is not recommended for through-hole film capacitors. Exposing capacitors to a soldering profile in excess of the recommended limits may result in degradation or permanent damage to the capacitors.

Do not place the polypropylene capacitor through an adhesive curing oven to cure resin for surface-mount components. Insert through-hole parts after curing the surface mount parts. Consult KEMET to discuss the actual temperature profile in the oven, if through-hole components must pass through the adhesive curing process. A maximum of two soldering cycles is recommended. Allow time for the capacitor surface temperature to return to a normal temperature before the second soldering cycle.

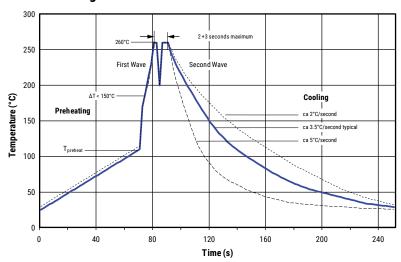
#### **Manual Soldering Recommendations**

Following is the recommendation for manual soldering with a soldering iron.



Soldering iron tip temperature should be set at 350°C (+10°C maximum), with the soldering duration not to exceed more than 3 seconds.

#### **Wave Soldering Recommendations**





# **Soldering Process cont.**

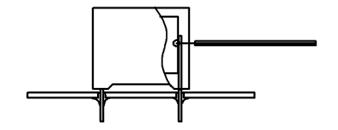
#### **Wave Soldering Recommendations cont'd**

1. The table indicates the maximum setup temperature for the soldering process.

Dielectric film material	Maximun	n Preheat Tem	Maximum Peak Soldering Temperature			
	Capacitor Pitch ≤ 10 mm	Capacitor Pitch = 15 mm	Capacitor Pitch > 15 mm	Capacitor Pitch ≤ 15 mm	Capacitor Pitch > 15 mm	
Polyester	130°C	130°C	130°C	270°C	270°C	
Polypropylene	100°C	110°C	130°C	260°C	270°C	
Paper	130°C	130°C	140°C	270°C	270°C	
Polyphenylene Sulphide	150°C	150°C	160°C	270°C	270°C	

2. The maximum temperature measured inside the capacitor: set the temperature so that inside the element the maximum temperature is below the limit.

Dielectric Film Material	Maximum Temperature Measured Inside the Element
Polyester	160°C
Polypropylene	110°C
Paper	160°C
Polyphenylene Sulphide	160°C



Temperature monitored inside the capacitor.

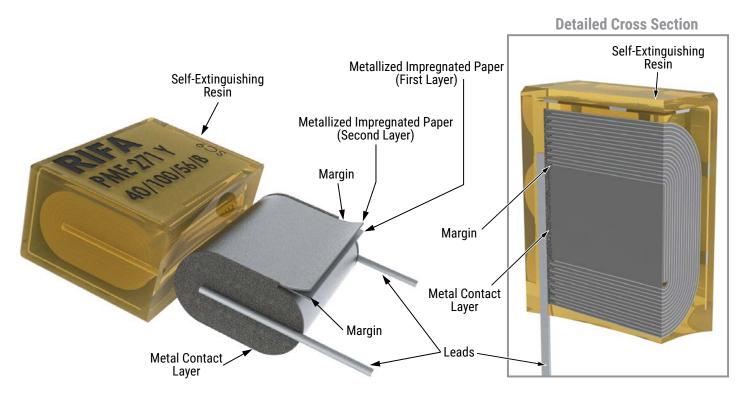
#### **Selective Soldering Recommendations**

Selective dip soldering is a variation of reflow soldering. In this method, the printed circuit board with through-hole components to be soldered is preheated and transported over the solder bath, as in normal flow soldering, without touching the solder. When the board is over the bath, it is stopped. Pre-designed solder pots are lifted from the bath with molten solder, only at the places of the selected components, and pressed against the lower surface of the board to solder the components.

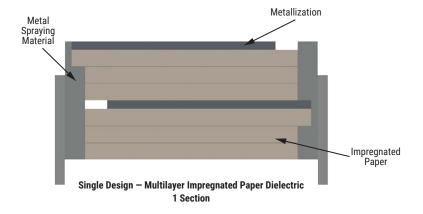
The temperature profile for selective soldering is similar to the double wave flow soldering outlined in this document. **However, instead of two baths, there is only one with a time from 3 to 10 seconds.** In selective soldering, the risk of overheating is greater than in double wave flow soldering. Great care must be taken so that the parts do not overheat.



#### Construction

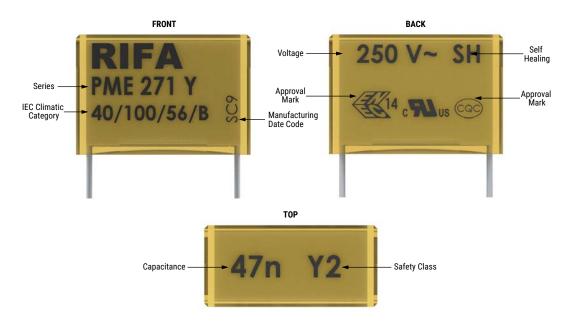


# **Winding Scheme**





# **Marking**



# **Packaging Quantities**

Lead Spacing (mm)	Thickness (mm)	Height (mm)	Length (mm)	Bulk Short Leads	Bulk Long Leads	Standard Reel 360 mm	Large Reel 500 mm	Ammo Formed
	3.9	7.5	13.5	2,000	1,000	700	1,400	800
10.2	4.1	8.2	13.5	2,000	1,000	600		780
	5.1	10.5	13.5	1,600	800	600	1,200	630
				·				
	5.5	12.5	18.0	1,000	500	600		
	6.5	12.5	18.0	600	400	400		
	7.5	14.5	18.0	600	400	400		
	8.5	16.0	18.0	400	250	400		
15.0	5.2	10.5	18.5	1,000	500	600		
15.2	5.5	11.0	18.5	1,000	500	500		
	6.0	12.5	18.5	600	400	400		
	7.3	13.0	18.5	600	400	400	800	
	7.8	13.5	18.5	600	400	400		
	8.5	14.3	18.5	500	300	350		
				·	·		· [	
	7.6	14.0	24.0	1,500	250	250	500	
20.3	8.4	14.0	24.0	1,200	200	250	500	
20.5	9.0	15.0	24.0	1,500	200	250		
	11.3	16.5	24.0	1,000	150	180	400	
	10.6	16.1	00.5	1.000	150			
	10.6	16.1	30.5	1,000	150			
25.4	10.5	17.3	30.5	1,000	100			
	12.1	19.0	30.5	800	100			
	15.3	22.0	30.5	600	75			

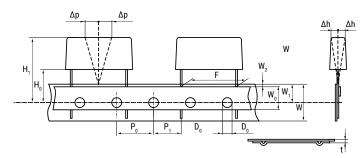


# Lead Taping & Packaging (IEC 60286-2)

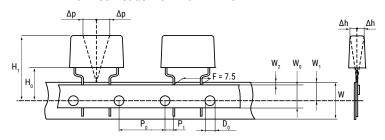
#### Lead Spacing 10.2 - 15.2 mm

# $H_1$ $H_2$ $M_2$ $M_3$ $M_4$ $M_4$ $M_5$ $M_4$ $M_5$ $M_5$

#### Lead Spacing 20.3 - 22.5 mm



Formed Leads from 10.2 - 7.5 mm



# **Taping Specification**

	Dimensions in mm										
Lead Spacing	+0.6/-0.1	F	Formed 7.5	10.2	15.2	20.3	22.5	F			
Carrier Tape Width	±0.5	W	18	18	18	18	18	18 +1/-0.5			
Hold-Down Tape Width	Minimum	W <sub>o</sub>	5	5	5	5	5				
Position of Sprocket Hole	±0.5	W <sub>1</sub>	9	9	9	9	9	9 +0.75/-0.5			
Distance Between Tapes	Maximum	$W_2$	3	3	3	3	3	3			
Sprocket Hole Diameter	±0.2	D <sub>0</sub>	4	4	4	4	4	4			
Feed Hole Lead Spacing	±0.3	P <sub>0</sub> <sup>(1)</sup>	12.7(4)	12.7	12.7	12.7	12.7	12.7			
Distance Lead – Feed Hole	±0.7	P <sub>1</sub>	3.75	7.6	5.1	8.9	5.3	P <sup>1</sup>			
Deviation Tape - Plane	Maximum	Δр	1.3	1.3	1.3	1.3	1.3	1.3			
Lateral Deviation	Maximum	Δh	2	2	2	2	2	2			
Total Thickness	±0.2	t	0.7	0.7	0.7	0.7	0.9 Maximum	0.9 Maximum			
Sprocket Hole/Cap Body	Nominal	$H_0^{(2)}$	18 +2/-0	18 +2/-0	18 +2/-0	18 +2/-0	18.5 ±0.5	18 +2/-0			
Sprocket Hole/Top of Cap Body	Maximum	H <sub>1</sub> <sup>(3)</sup>	43	43	43	58	58	58 Maximum			

<sup>(1)</sup> Maximum cumulative feed hole error, 1 mm per 20 parts

<sup>(2) 16.5</sup> mm available on request

<sup>(3)</sup> Depending on case size

<sup>(4) 15</sup> mm available on request



### **KEMET Electronics Corporation Sales Offices**

For a complete list of our global sales offices, please visit www.kemet.com/sales.

#### **Disclaimer**

All product specifications, statements, information and data (collectively, the "Information") in this datasheet are subject to change. The customer is responsible for checking and verifying the extent to which the Information contained in this publication is applicable to an order at the time the order is placed. All Information given herein is believed to be accurate and reliable, but it is presented without guarantee, warranty, or responsibility of any kind, expressed or implied.

Statements of suitability for certain applications are based on KEMET Electronics Corporation's ("KEMET") knowledge of typical operating conditions for such applications, but are not intended to constitute – and KEMET specifically disclaims – any warranty concerning suitability for a specific customer application or use. The Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by KEMET with reference to the use of KEMET's products is given gratis, and KEMET assumes no obligation or liability for the advice given or results obtained.

Although KEMET designs and manufactures its products to the most stringent quality and safety standards, given the current state of the art, isolated component failures may still occur. Accordingly, customer applications which require a high degree of reliability or safety should employ suitable designs or other safeguards (such as installation of protective circuitry or redundancies) in order to ensure that the failure of an electrical component does not result in a risk of personal injury or property damage.

Although all product-related warnings, cautions and notes must be observed, the customer should not assume that all safety measures are indicted or that other measures may not be required.

# **X-ON Electronics**

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Film Capacitors category:

Click to view products by Kemet manufacturer:

Other Similar products are found below:

F339X134748MIP2T0 750-1018 FKP1-1000160010P15 FKP1-1500160010P15 FKP1R031507E00JYSD FKP1U024707E00KYSD 82DC4100CK60J 82EC1100DQ50K PFR5101J100J11L16.5TA18 PME261JB5220KR19T0 A451GK223M040A A521HH333M035C A561ED221M450A QXJ2E474KTPT QXL2B333KTPT R49AN347000A1K EEC2G505HQA406 B25668A6676A375 B25673A4282E140 BFC233868148 BFC2370GC222 C3B2AD44400B20K 950CQW5H-F SCD105K122A3-22 SCD155K162A3X44-F 2N3155 A571EH331M450A FKP1-2202KV5P15 FKS3-680040010P10 QXL2E473KTPT 445450-1 B25669A3996J375 46KI322000M1M 46KR415050M1K 4BSNBX4100ZBFJ MKP383510063JKP2T0 MKPY2-.02230020P15 MKT 1813-368-015 4055292001 46KN410000N1K EEC2E106HQA405 EEC2G205HQA402 EEC2G805HQA415 82EC2150DQ50K 288P22494H101 PHE841ED6150MR17T0 B25620B118K883 B25620B158K883 BFC2370GC223 BFC237022472